



# SOT762-1

plastic, leadless dual in-line compatible thermal enhanced very thin quad flat package; 14 terminals; 0.5 mm pitch; 3 mm x 2.5 mm x 1 mm body

17 August 2021

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	DHVQFN14
<b>Package type industry code</b>	DHVQFN14
<b>Package style descriptive code</b>	DHVQFN (DIL-compatible thermal enhanced very thin quad flatpack; no leads)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	---
<b>JEDEC package outline code</b>	MO-241
<b>JEITA package outline code</b>	---
<b>Mounting method type</b>	S (surface mount)
<b>Number of package outline detail graphic references</b>	0
<b>Issue date</b>	5-5-2015
<b>Manufacturer package code</b>	SOT762
<b>Footprint dimensions (mm)</b>	4.25 x 3.75
<b>Footprint area (mm<sup>2</sup>)</b>	15.94

Table 1. Package summary

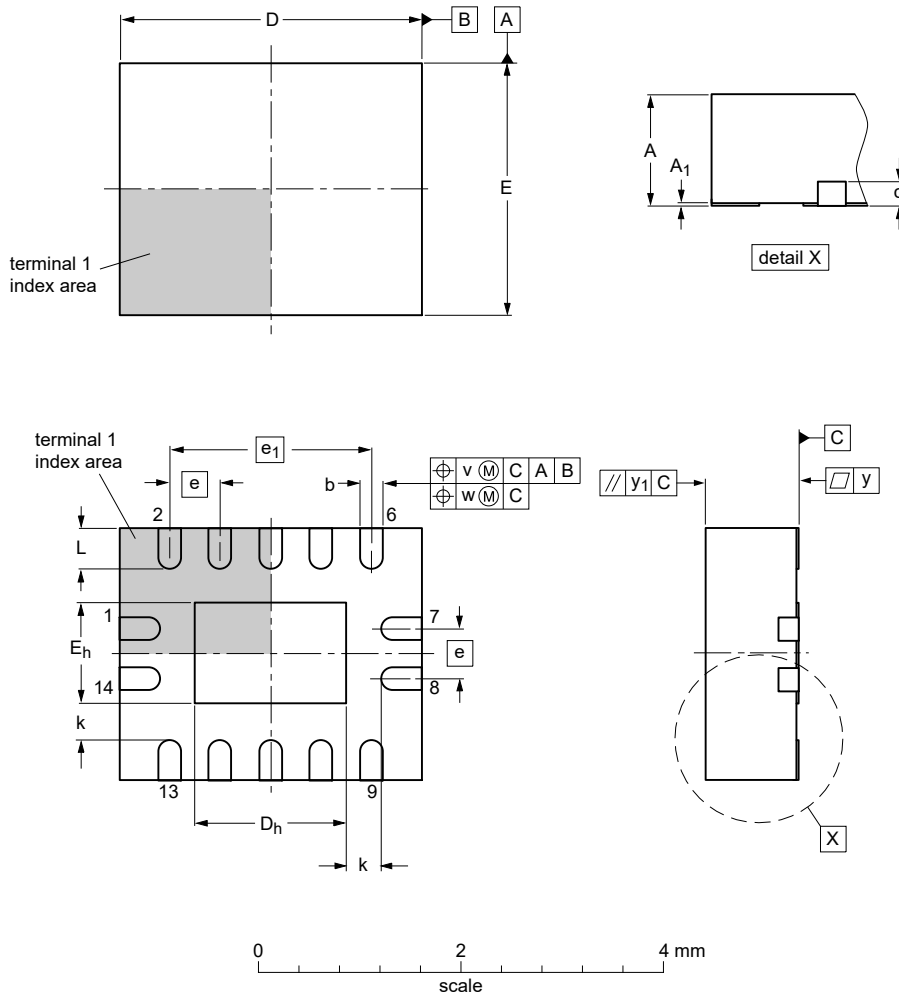
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.9	-	3	3.1	mm
E	package width	2.4	-	2.5	2.6	mm
A	seated height	-	-	-	1	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	14	-	

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## 2. Package outline

DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm

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Dimensions (mm are the original dimensions)

Unit	A <sup>(1)</sup>	A <sub>1</sub>	b	c	D <sup>(1)</sup>	D <sub>h</sub>	E <sup>(1)</sup>	E <sub>h</sub>	e	e <sub>1</sub>	k	L	v	w	y	y <sub>1</sub>
mm	max	1	0.05	0.30	3.1	1.65	2.6	1.15				0.5				
	nom		0.02	0.25	3.0	1.50	2.5	1.00	0.5	2		0.4	0.1	0.05	0.05	0.1
	min		0.00	0.18	2.9	1.35	2.4	0.85			0.2	0.3				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

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Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT762-1		MO-241				15-04-10 15-05-05

Fig. 1. Package outline DHVQFN14 (SOT762-1)

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### 3. Soldering

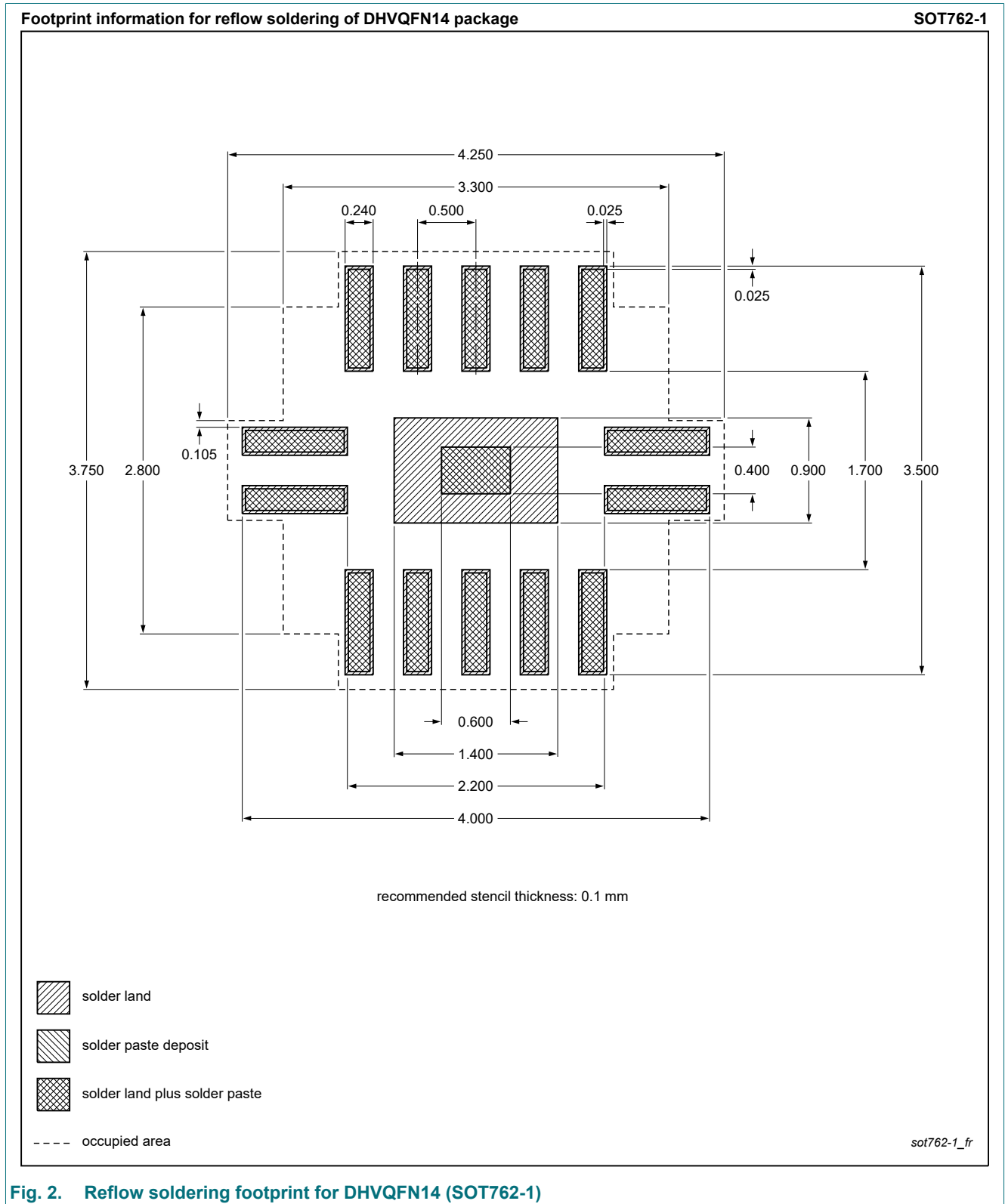


Fig. 2. Reflow soldering footprint for DHVQFN14 (SOT762-1)

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